

Product brief

Microphone flex evaluation kit

An evaluation system for XENSIV™ MEMS microphones

Infineon's XENSIV™ MEMS microphone flex evaluation kit allows for evaluation with minimal effort. Its small size and flexibility enables direct placement of the flex board into a prototype.

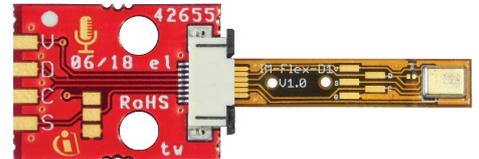
Each flex kit consists of five flex boards and one adapter board.

The digital flex board is equipped with a digital PDM output microphone and a 0.1 µF supply bypass capacitor. It can be connected to a 6-position ZIF connector with a 0.5 mm pin spacing, such as the Molex 0527450697, or wires can be soldered directly on the flex board. The analog flex board is equipped only with the differential MEMS microphone.

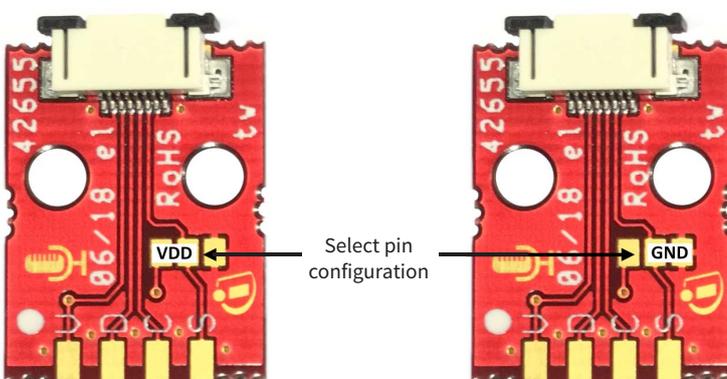
The adapter board has a 6-position ZIF and a 2.54 mm board-to-board connector. The adapter board provides the ability to configure the select pin of digital microphone to VDD or Ground.

Key features

- > Quick and easy connection to evaluation system
- > Small size: 25 mm x 4.5 mm
- > Pre soldered MEMS microphone
- > Configurable select pin configuration for digital microphones



Digital microphone select pin configuration



Flex adapter board pin configuration

Pin number	Symbol	Digital	Analog
1	V	VDD	VDD
2	D	Data	OUT +
3	C	Clock	OUT -
4	S	Select	Not used
	Back side	GND	GND

For further information on available products with flex board, please refer to the Infineon Technologies web page or contact local sales, or application engineer.

